



# SOT684-9

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals

5 March 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN56
<b>Package type industry code</b>	HVQFN56
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-05-2009
<b>Manufacturer package code</b>	SOT684

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
seated height	0.8	0.85	1	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



2 Package outline

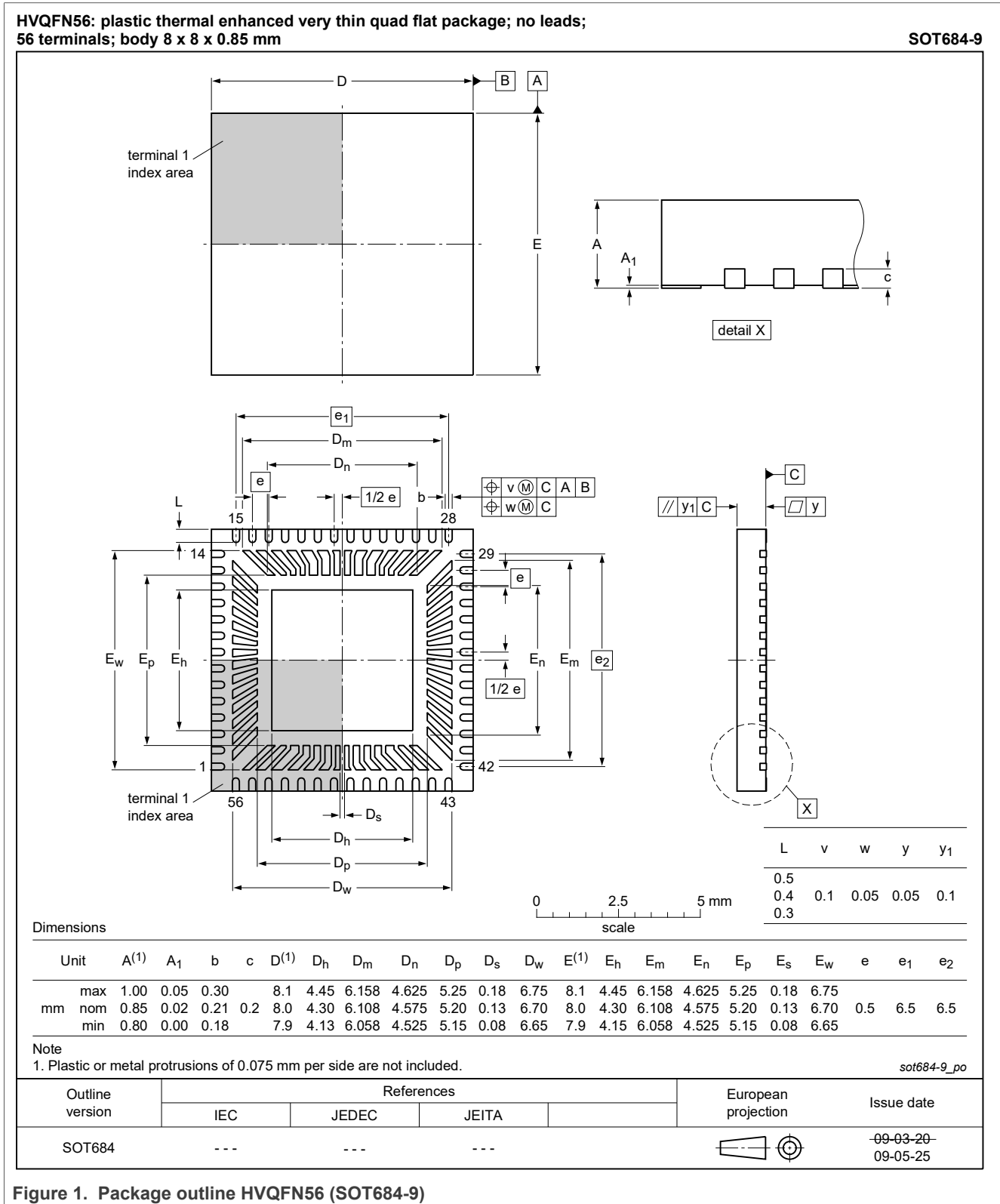


Figure 1. Package outline HVQFN56 (SOT684-9)

### 3 Legal information

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